

LGAD timing layer

FBK TI-LGADs with 55×55 pixels, $55 \mu\text{m}$ pitch

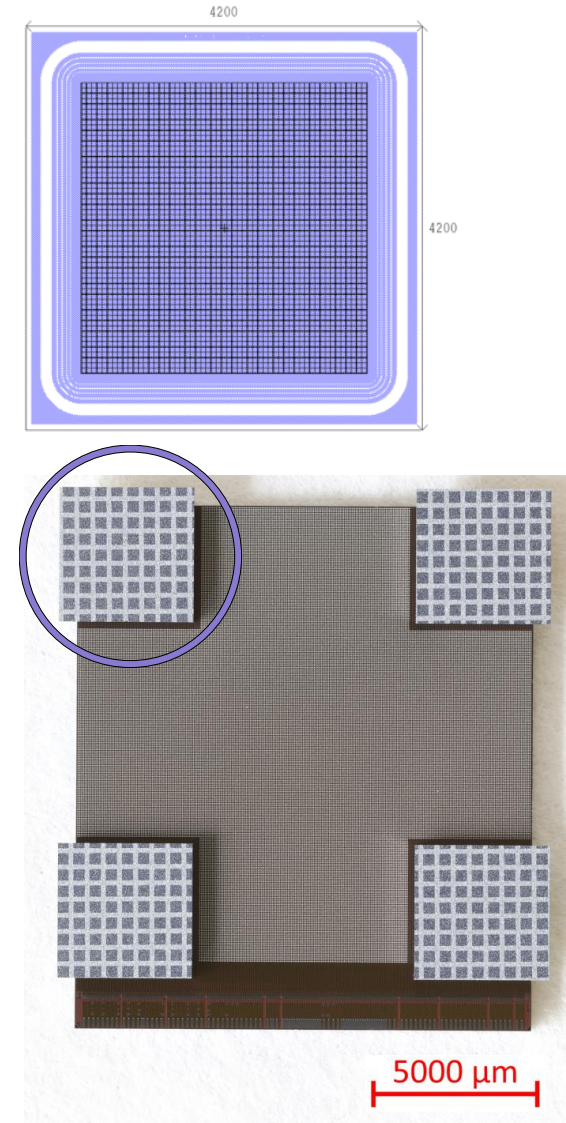
Samples from two different wafers: W1 and W3.

Two versions each:

- ▶ contact type 2, pixel V3, 1 trench
- ▶ contact type 2, pixel V3, 2 trench

Sent to IZM for bump bonding to **Timepix3 chips**

Seven Timepix3 LGAD “Quad” assemblies received



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Testbeam time September 2024:

- ▶ One week in DESY II TB area 24
- ▶ Two sets of measurements:
 - ▶ 1300 μm pixel size samples with oscilloscope
 - ▶ 55 μm pixel size samples with Timepix3

